

## COPY OF PAPERS ORIGINALLY FILED

Examiner:

Art Unit:

A. Chambliss

TECHNOLOGY CENTER 2800

2814

## STATES PATENT AND TRADEMARK OFFICE

Applicants

K. TATSUMI et al.

Serial No.

09/254,118

Filed

May 19, 1999

For

METHOD OF PARTIALLY PLATING SUBSTRATE FOR

ELECTRONIC DEVICES

Assistant Commissioner

for Patents

Washington, D.C. 20231

## TRANSMITTAL LETTER

SIR:

Transmitted herewith is an Amendment/Response in the above-identified patent application.

[X]

No additional fee is required.

The fee has been calculated as shown below.

						SMALL ENTITY				OTHER THAN A SMALL ENTITY		
CLAIMS REMAINING AFTER AMENDMENT		PREVI	HIGHEST NO. PREVIOUSLY PRESE PAID FOR EXTRA			RATE	ADDIT	r. <u>or</u>	RATE	_	ADDIT.	
TOTAL	10	MINUS	20	=	0	x6 =	\$		x18 =	\$	0	
INDEP.	1	MINUS	3	=	0	x18 =	\$		x80 =	\$	0.00	
[]FIR	ST PRE	ENTATION	OF	MUI	TIPLE	<b>x</b> 60 =	\$		x270 =	\$	0.00	
DEP. CLAIM TOTAL												
					ADDIT.	. FEE	\$	OR		\$	0.00	

[X] The Commissioner is hereby authorized to charge fees 37 CFR 1.16 and 1.17 which may be required to Deposit Account 11-0600. A duplicate of this paper is enclosed.

[X] A petition for a two (2) month extension of time and Deposit Account authorization to cover the extension fee are enclosed.

Respectfully submitted,

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on March 22, 2002

KENYON & KENYON

Req. No. 29,182

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